

# DuPont™ EKC Technology

## Wafer Level Packaging Photoresist Remover

For Complete Resist Removal

### Product Description

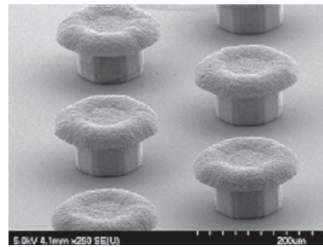
WLP photoresist removers are formulations optimized to effectively remove thick negative liquid resists used for wafer bumping by solder electroplating or stencil printing. The product is designed for use in spray processing equipment and wet benches.

### Features

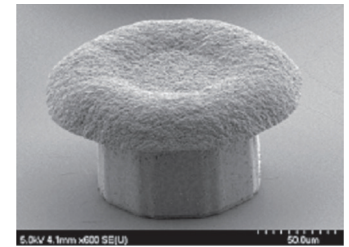
- Formulated to give complete resist removal and eliminate resist re-deposit
- Short stripping time requirement
- High wafer capacity with long bathlife
- Compatible with wet bench and spray process equipment
- Operates at moderate temperatures
- Low evaporation rate at operating temperature
- Completely water rinsable
- High flashpoint
- Compatible with copper and a wide variety of under-bump metallization (UMB materials)
- Compatible with conventional and lead-free solders

### Benefits

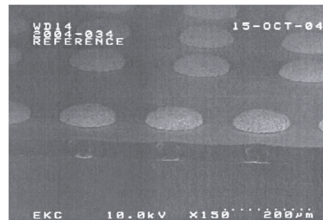
- No polymer residues around bumps
- Eliminates UBM etch masking
- Offers flexibility in equipment choice
- Higher throughput
- Resource conservation through reduced stripping time and temperature
- Reduced material use and disposal from less frequent bath or tank changes
- Lower overall operating costs



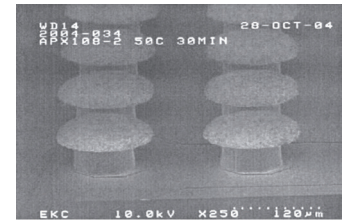
After PR Removal



After PR Removal



Before PR Removal



After PR Removal



[ekctech.dupont.com](http://ekctech.dupont.com)

For more information on DuPont™ EKC Technology or other DuPont products, please visit our website.

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**CAUTION:** Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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